

# 1:2 CML Fanout Buffer with Selectable Clock Input

#### **Features**

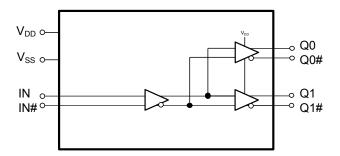
- One current mode logic (CML), High-speed current steering logic (HCSL), or low-voltage positive emitter-coupled logic (LVPECL) input pair distributed to two CML output pairs
- 20-ps maximum output-to-output skew
- 480-ps maximum propagation delay
- 0.15-ps maximum additive RMS phase jitter at 156.25 MHz (12-kHz to 20-MHz offset)
- Up to 1.5 GHz operation
- 8-pin thin shrunk small outline package (TSSOP) package
- 2.5-V or 3.3-V operating voltage [1]
- Commercial and industrial operating temperature range

#### **Functional Description**

The CY2DM1502 is an ultra-low noise, low-skew, low-propagation delay 1:2 CML, HCSL, or LVPECL to CML fanout buffer targeted to meet the requirements of high-speed clock distribution applications. The device has a fully differential internal architecture that is optimized to achieve low additive jitter and low skew at operating frequencies of up to 1.5 GHz.

For a complete list of related documentation, click here.

### **Logic Block Diagram**



#### Note

Input AC-coupling capacitors are required for voltage-translation applications.



#### **Contents**

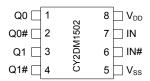
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#### **Pinouts**

Figure 1. 8-pin TSSOP Package pinout



# **Pin Definitions**

Pin No.	Pin Name	Pin Type	Description
1, 3	Q(0:1)	Output	CML output clocks
2, 4	Q(0:1)#	Output	CML complementary output clocks
5	V <sub>SS</sub>	Power	Ground
6	IN#	Input	CML/HCSL/LVPECL complementary input clock
7	IN	Input	CML/HCSL//LVPECL input clock
8	$V_{DD}$	Power	Power supply



# **Absolute Maximum Ratings**

Parameter	Description	Condition	Min	Max	Unit
$V_{DD}$	Supply voltage	Nonfunctional	-0.5	4.6	V
V <sub>IN</sub> <sup>[2]</sup>	Input voltage, relative to V <sub>SS</sub>	Nonfunctional	-0.5	lesser of 4.0 or V <sub>DD</sub> + 0.4	V
V <sub>OUT</sub> <sup>[2]</sup>	DC output or I/O voltage, relative to V <sub>SS</sub>	Nonfunctional	-0.5	lesser of 4.0 or V <sub>DD</sub> + 0.4	٧
T <sub>S</sub>	Storage temperature	Nonfunctional	<b>–</b> 55	150	°C
ESD <sub>HBM</sub>	Electrostatic discharge (ESD) protection (Human body model)	JEDEC STD 22-A114-B	2000	_	V
L <sub>U</sub>	Latch up		Meets or exceeds JEDEC Spec JESD78B IC Latch-up Test		_
UL-94	Flammability rating	At 1/8 in	V-0		
MSL	Moisture sensitivity level		3		

# **Operating Conditions**

Parameter	Description	Condition	Min	Max	Unit
$V_{DD}$	Supply voltage	2.5-V supply	2.375	2.625	V
		3.3-V supply	3.135	3.465	V
T <sub>A</sub>	Ambient operating temperature	Commercial	0	70	°C
		Industrial	-40	85	°C
t <sub>PU</sub>	Power ramp time	Power-up time for V <sub>DD</sub> to reach minimum specified voltage (power ramp must be monotonic).	0.05	500	ms

#### Note

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<sup>2.</sup> The voltage on any I/O pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.



# **DC Electrical Specifications**

(V<sub>DD</sub> = 3.3 V  $\pm$  5% or 2.5 V  $\pm$  5%; T<sub>A</sub> = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

Parameter	Description	Condition	Min	Max	Unit
I <sub>DD</sub>	Operating supply current	All CML outputs floating (internal I <sub>DD</sub> )	-	50	mA
V <sub>IH</sub>	Input high voltage, CML/HCSL/LVPECL inputs IN and IN#		-	V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input low voltage, CML/HCSL/LVPECL inputs IN and IN#		-0.3	_	V
V <sub>ID</sub> [3]	Input differential amplitude	See Figure 2 on page 7	0.4	1.0	V
V <sub>ICM</sub>	Input common mode voltage	See Figure 2 on page 7	0.2	V <sub>DD</sub> – 0.2	V
I <sub>IH</sub>	Input high current, CML/HCSL/LVPECL inputs IN and IN#	Input = $V_{DD}^{[4]}$	-	150	μА
I <sub>IL</sub>	Input low current, CML/HCSL/LVPECL inputs IN and IN#	Input = $V_{SS}^{[4]}$	-150	-	μА
V <sub>OH</sub>	CML output high voltage	Terminated with 50 $\Omega$ to $V_{DD}^{[5]}$	V <sub>DD</sub> – 0.1	-	V
V <sub>OL</sub>	CML output low voltage	Terminated with 50 $\Omega$ to $V_{DD}^{[5]}$	V <sub>DD</sub> - 0.7	V <sub>DD</sub> – 0.3	V
C <sub>IN</sub>	Input capacitance	Measured at 10 MHz; per pin	_	3	pF

#### **Thermal Resistance**

Parameter [6]	Description	Test Conditions	8-pin TSSOP	Unit
$\theta_{JA}$	,	Test conditions follow standard test methods and procedures for measuring thermal impedance, in	162	°C/W
$\theta_{JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	29	°C/W

- 3. V<sub>ID</sub> minimum of 400 mV is required to meet all output AC Electrical Specifications. The device is functional with V<sub>ID</sub> minimum of greater than 200 mV.
  4. Positive current flows into the input pin, negative current flows out of the input pin.
- 5. Refer to Figure 3 on page 7.
- 6. These parameters are guaranteed by design and are not tested.

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# **AC Electrical Specifications**

(V<sub>DD</sub> = 3.3 V  $\pm$  5% or 2.5 V  $\pm$  5%; T<sub>A</sub> = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

Parameter	Description	Condition	Min	Тур	Max	Unit
F <sub>IN</sub>	Input frequency		DC	_	1.5	GHz
F <sub>OUT</sub>	Output frequency	F <sub>OUT</sub> = F <sub>IN</sub>	DC	_	1.5	GHz
V <sub>PP</sub>	CML differential output voltage	Fout = DC to 150 MHz	250	_	700	mV
	peak-to-peak, single-ended. Terminated with 50 $\Omega$ to $V_{DD}^{[5]}$	Fout = >150 MHz to 1.5 GHz	250	_	600	mV
t <sub>PD</sub> <sup>[7]</sup>	Propagation delay input pair to output pair	Input rise/fall time < 1.5 ns (20% to 80%)	-	_	480	ps
t <sub>ODC</sub> <sup>[8]</sup>	Output duty cycle	50% duty cycle at input Frequency range up to 1 GHz	48	-	52	%
t <sub>SK1</sub> <sup>[9]</sup>	Output-to-output skew	Any output to any output, with same load conditions at DUT	-	-	20	ps
t <sub>SK1 D</sub> <sup>[9]</sup>	Device-to-device output skew	Any output to any output between two or more devices. Devices must have the same input and have the same output load.	_	_	150	ps
PN <sub>ADD</sub>	Additive RMS phase noise 156.25-MHz Input	Offset = 1 kHz	_	-	-120	dBc/ Hz
	Rise/fall time < 150 ps (20% to 80%)	Offset = 10 kHz	_	-	-130	dBc/ Hz
	V <sub>ID</sub> > 400 mV	Offset = 100 kHz	_	_	-135	dBc/ Hz
		Offset = 1 MHz	_	_	-145	dBc/ Hz
		Offset = 10 MHz	_	_	-153	dBc/ Hz
		Offset = 20 MHz	_	_	-155	dBc/ Hz
t <sub>JIT</sub> <sup>[10]</sup>	Additive RMS phase jitter (Random)	156.25 MHz, 12 kHz to 20 MHz offset; input rise/fall time < 150 ps (20% to 80%), V <sub>ID</sub> > 400 mV	-	-	0.15	ps
t <sub>R</sub> , t <sub>F</sub> <sup>[11]</sup>	Output rise/fall time	50% duty cycle at input, 20% to 80% of full swing (V <sub>OL</sub> to V <sub>OH</sub> ) Input rise/fall time < 1.5 ns (20% to 80%) Measured at 1 GHz	-	_	250	ps

#### Notes

<sup>7.</sup> Refer to Figure 4 on page 7.
8. Refer to Figure 5 on page 7.
9. Refer to Figure 6 on page 8.
10. Refer to Figure 7 on page 8.
11. Refer to Figure 8 on page 8.



Figure 2. Input Differential and Common Mode Voltages



Figure 3. Output Differential Voltage

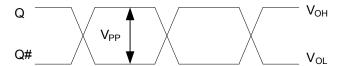


Figure 4. Input to Any Output Pair Propagation Delay

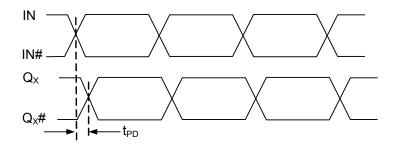
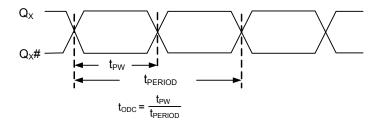


Figure 5. Output Duty Cycle



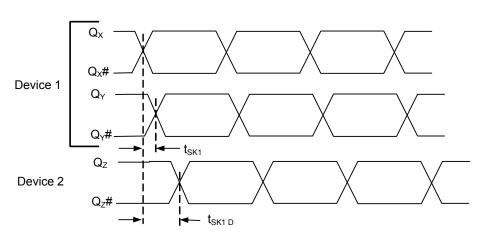


Figure 6. Output-to-Output and Device-to-Device Skew

Figure 7. RMS Phase Jitter

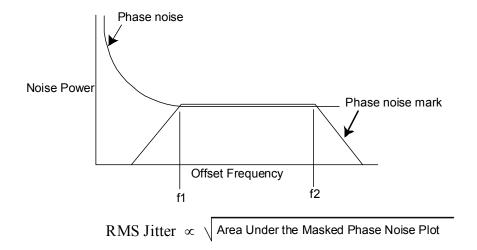
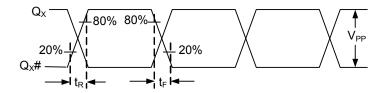


Figure 8. Output Rise/Fall Time

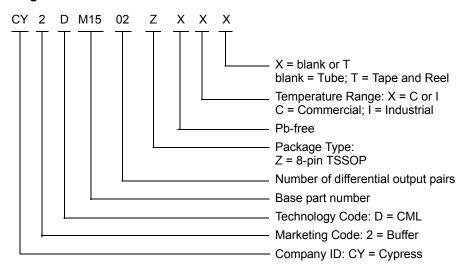




# **Ordering Information**

Part Number	Туре	Production Flow	
Pb-free			
CY2DM1502ZXI	8-pin TSSOP	Industrial, –40 °C to 85 °C	
CY2DM1502ZXIT	8-pin TSSOP tape and reel	Industrial, –40 °C to 85 °C	

#### **Ordering Code Definitions**

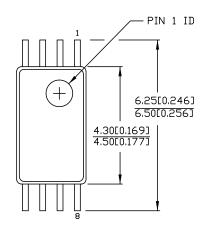




# **Package Diagram**

#### Figure 9. 8-pin TSSOP (4.40 MM Body) Z08.173/ZZ08.173 Package Outline, 51-85093

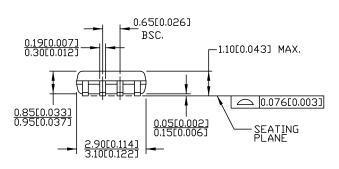
# 8 Lead TSSOP 4.40 MM BODY

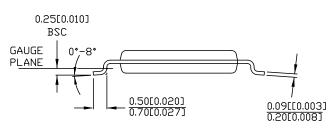


DIMENSIONS IN MM[INCHES] MIN. MAX.

REFERENCE JEDEC MO-153

	PART #
Z08.173	STANDARD PKG.
ZZ08.173	LEAD FREE PKG.





51-85093 \*E

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# **Acronyms**

Table 1. Acronyms Used in this Document

Acronym	Description
CML	current mode logic
ESD	electrostatic discharge
HBM	human body model
HCSL	high-speed current steering logic
JEDEC	joint electron devices engineering council
LVDS	low-voltage differential signal
LVCMOS	low-voltage complementary metal oxide semiconductor
LVPECL	low-voltage positive emitter-coupled logic
RMS	root mean square
TSSOP	thin shrunk small outline package

## **Document Conventions**

#### **Units of Measure**

Table 2. Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
dBc	decibels relative to the carrier
GHz	gigahertz
Hz	hertz
kΩ	kilohm
μΑ	microampere
μF	microfarad
μs	microsecond
mA	milliampere
ms	millisecond
mV	millivolt
MHz	megahertz
ns	nanosecond
Ω	ohm
pF	picofarad
ps	picosecond
V	volt
W	watt



# **Document History Page**

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	2782891	CXQ	10/09/09	New Datasheet.
*A	2838916	CXQ	01/05/2010	Changed status from "ADVANCE" to "PRELIMINARY". Changed from 0.34 ps to 0.25 ps maximum additive jitter in "Features" on pag 1 and in $t_{JIT}$ in the AC Electrical Specs table on page 4. Added $t_{PU}$ spec to the Operating Conditions table on page 2. Removed $V_{OH}$ spec maximum of $V_{DD}$ in the DC Electrical Specs table on pag 3. Changed $V_{OL}$ spec min from $V_{DD}$ - 0.6V to $V_{DD}$ - 0.7V; changed max from $V_{D}$ - 0.4V to $V_{DD}$ - 0.3V in the DC Electrical Specs table on page 3. Removed $V_{OD}$ spec of minimum 300 mV, maximum 450 mV in the DC Electrical Specs table on page 3. Added $R_{P}$ spec in the DC Electrical Specs table on page 3. Min = 60 k $\Omega$ , Ma = 140 k $\Omega$ . Added a measurement definition for $C_{IN}$ in the DC Electrical Specs table on page 3. Added $V_{PP}$ spec to the AC Electrical Specs table on page 4. $V_{PP}$ max = 700 mV for DC - 150 MHz and max = 600 mV for 150 MHz to 1.5 GHz. $V_{PP}$ min = 250 mV over the entire range. Changed letter case and some names of all the timing parameters in the AC Electrical Specs table on page 4 to be consistent with EROS. Lowered all additive phase noise mask specs by 3 dB in in the AC Electrica Specs table on page 4. Added condition to $t_{R}$ and $t_{F}$ specs in the AC Electrical specs table on page 4 that input rise/fall time must be less than 1.5 ns (20% to 80%).
*B	3011766	CXQ	08/20/2010	Changed letter case and some names of all the timing parameters in Figure 3, 4, 5, 6 and 8, to be consistent with EROS.   Changed from 0.25 ps to 0.11 ps maximum additive jitter in "Features" on page 1 and in $t_{JIT}$ in the AC Electrical Specs table.   Added note 3 to describe $I_{IH}$ and $I_{IL}$ specs.   Removed reference to data distribution from "Functional Description".   Changed $R_P$ for diff inputs from 100 k $\Omega$ to 150 k $\Omega$ in the Logic Block Diagra and from 60 k $\Omega$ min / 140 k $\Omega$ max to 90 k $\Omega$ min / 210 k $\Omega$ max in the DC Electric Specs table.   Added max $V_{ID}$ of 1.0V in DC Electrical Specs table.   Updated phase noise specs for 1 k/10 k/100 k/1 M/10 M/20 MHz offset to -120/-130/-135/-150/-150/-150dBc/Hz, respectively, in the AC Electrical Spectable.   Added "Frequency range up to 1 GHz" condition to $t_{ODC}$ spec.   Updated package diagram.
*0	0047050	0)/0	00/07/0040	Added Acronyms and Ordering Code Definition.
*C	3017258	CXQ	08/27/2010	Corrected Output Rise/Fall time diagram.
*D	3100234	CXQ	11/18/2010	Updated Phase jitter to 0.15ps max from 0.11ps max. Changed $V_{IN}$ and $V_{OUT}$ specs from 4.0V to "lesser of 4.0 or $V_{DD}$ + 0.4" Removed 200mA min LU spec, replaced with "Meets or exceeds JEDEC Speck JESD78B IC Latchup Test" Removed $R_P$ spec for differential input clock pins $IN_X$ and $IN_X$ #. Changed $C_{IN}$ condition to "Measured at 10 MHz". Changed $PN_{ADD}$ specs for 1MHz, 10MHz, and 20MHz offsets. Added condition "Measured at 1 GHz" to $t_R$ , $t_F$ specs.
*E	3137726	CXQ	01/13/2011	Removed "Preliminary" status heading. Removed resistors from IN/IN# in Logic Block Diagram.
*F	3090938	CXQ	02/25/2011	Post to external web.

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# **Document History Page** (continued)

Document Title: CY2DM1502, 1:2 CML Fanout Buffer with Selectable Clock Input Document Number: 001-56315						
Revision	ECN	Orig. of Change	Submission Date	Description of Change		
*G	3410372	PURU	10/18/2011	Adding HCSL to Features, Functional Description, Pin Definitions, and DC Electrical Specifications sections. The min value of $V_{\rm ICM}$ is changed from 0.5 to 0.2 in DC Electrical Specifications.		
*H	3878396	PURU	01/21/2013	Updated to new template.		
*	4587249	PURU	12/04/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end. Updated Ordering Information: Removed the prune part numbers CY2DM1502ZXC and CY2DM1502ZXCT. Updated Package Diagram: spec 51-85093 – Changed revision from *D to *E.		
*J	5272915	PSR	05/16/2016	Added Thermal Resistance. Updated to new template.		
*K	5966682	AESATMP8	11/14/2017	Updated logo and Copyright.		



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